IEEE P802.3df 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet Task Force

February 2022 Electronic Session

Approved Meeting Minutes, prepared by John D'Ambrosia

Session called to order at 10:03 am ET (all times ET), 03 Feb 2022

Meeting called to order by John D'Ambrosia, IEEE P802.3df Task Force Chair

Presentation #1	**Agenda and General Information**
Presenters	John D'Ambrosia
URL	https://www.ieee802.org/3/df/public/22_02/agenda_3df_220203.pdf

Chair reviewed the agenda (Slide #2) and noted presentation order on Slide #3. Chair noted that straw polls might be taken during any meeting of the Feb 2022 session, pending need and time availability. He noted that any motions for the session would be considered @ the 24 Feb meeting, pending time permitting. Chair asked if there were any objections to the agenda (Slide #2), there were none, and the agenda was considered approved by unanimous consent.

Minutes – Jan 2022 session
https://www.ieee802.org/3/df/public/22_01/minutes_3df_2201_unapproved.pdf

Chair noted he had received a request to change "Meeting broke" to "Meeting recessed" in minutes.
Chair asked if there were any other corrections. There were none. Chair asked if there were any objections to approving the modified minutes. There were none, and the minutes were considered approved.

Chair reviewed the Task Force Project Information / Organization. See Slides #4. Chair noted the 4 task force reflectors, and indicated individuals needed to join each separately. Chair also noted that Task Force information, such as meeting announcements would be sent to stds-802-3-b400g@listserv@ieee.org.

Chair reviewed meeting decorum. See Slide #5.

Chair reviewed Ground Rules. See Slide #6.

Chair Reviewed Task Force Comment Phase. See Slide #7.

Slide #8 - Chair noted that the information regarding the IEEE SA Policies had been sent out, and requested that individuals review the following IEEE SA policies prior to the interim meeting –
- IEEE SA Patent policy
- IEEE SA Copyright Policy
- IEEE SA Participation Policy

Chair asked if anyone needed to review the policies at that time – there were no requests to do so.

Chair presented the third slide (See Slide #28) of the IEEE SA Patent Policy slides. Chair did call for Potentially Essential Patents, and no one came forward.

Chair presented the second slide (See Slide #33) of the IEEE SA Copyright Policy slides. Chair noted – "By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy."

Chair presented the second slide (See Slide #37) of the IEEE SA Participation Policy slides. Chair noted – "Participants in the IEEE-SA "individual process" shall act independently of others, including employers. By participating in standards

activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation."

Chair ruled Task Force voting, voting rights, and attendance. See Slides #9-10.

Chair noted that as of 31 Jan, there were no liaisons received for the Task Force to consider. See Slide #11.

Presentation #2   **Case Study: FEC architectures for 800 GbE**
Presenters   Kapil Shrikhande, Gary Nicholl
URL   https://www.ieee802.org/3/df/public/22_02/shrikhande_3df_01a_220203.pdf

General questions and discussion.
Chair announced his intent to create ad hocs aligning with the track structure of the Task Force. Email announcements of each ad hoc and their respective charter will be sent.

During the presentation some errors were noted. An update will be sent after the meeting (noted above).

Presentation #3   **Consideration on 100Gbps/lane PCS/FEC for 800GbE/1.6TbE**
Presenter   Leon Bruckman
URL   https://www.ieee802.org/3/df/public/22_02/bruckman_3df_01a_220203.pdf

General questions and discussion.

During the presentation some errors were noted. An update will be sent after the meeting (noted above).

Meeting break at 11:55am
Meeting reconvened at 12:00pm

Presentation #4   **Thoughts on the 800 Gb/s and 1.6 Tb/s PCS**
Presenters   Tom Huber
URL   https://www.ieee802.org/3/df/public/22_02/huber_3df_01a_220203.pdf

General questions and discussion.

During the presentation some errors were noted. An update will be sent after the meeting (noted above).

Presentation #5   **Baseline proposal for 800GbE and 1.6TbE electrical interfaces and PMDs using 100 Gbps/lane signaling**
Presenters   Kent Lusted
URL   https://www.ieee802.org/3/df/public/22_02/lusted_3df_01a_220203.pdf

Update to presentation that added supporters. Update noted above.

General questions and discussion.

Given that there were only a few minutes left in the meeting, the chair asked if there were any objections to taking the following straw poll requested by Kent Lusted. There were no objections.

Straw Poll #1	I support the proposed direction for 800GbE electrical interfaces and PMDs using 100 Gbps/lane signaling, per lusted_3df_01a_220203.pdf, slides 5-7
Results All	Yes – 41 No – 0 Need more information – 22 Abstain - 8

Chair reviewed future meetings. See Slide #12 of agenda presentation.

- It was noted that details of meetings for Mar 2022 session were still being worked out.
- Call for presentations was announced, and due date is 28 Feb 2022.
- Chair reminded everyone that registration was required for the March 2022 plenary.

Meeting recessed for the day at 1:11pm

IEEE P802.3df 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet Task Force

February 2022 Electronic Session

Session reconvened at 10:02 am ET (all times ET), 15 Feb 2022

Meeting called to order by John D'Ambrosia, IEEE P802.3df Task Force Chair

Chair showed the IMAT information.
Chair noted that the agenda deck had been updated to include announced meeting and ad hoc information. See https://www.ieee802.org/3/df/public/22_02/agenda_3df_b_220203.pdf

Chair noted that the information regarding the procedures had been sent out, and requested that individuals review the following IEEE SA policies prior to the interim meeting –
- IEEE SA Patent policy
- IEEE SA Copyright Policy
- IEEE SA Participation Policy

Chair asked if anyone needed to review the policies at that time – there were no requests to do so.

Chair presented the third slide (See Slide #29) of the IEEE SA Patent Policy slides. Chair did call for Potentially Essential Patents, and no one came forward.

Chair presented the second slide (See Slide #34) of the IEEE SA Copyright Policy slides. Chair noted – "By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy."

Chair presented the second slide (See Slide #38) of the IEEE SA Participation Policy slides. Chair noted – "Participants in the IEEE-SA "individual process" shall act independently of others, including employers. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation."

Presentation #6	FEC Code and Scheme Observation in 800G/1.6TbE
Presenters	Xinyuan Wang
URL	https://www.ieee802.org/3/df/public/22_02/wang_3df_01_220215.pdf

General questions and discussion.

Presentation #7	DSP and FEC considerations for 800GE & 1.6TE
Presenters	Yuchun Lu
URL	https://www.ieee802.org/3/df/public/22_02/lu_3df_01b_220215.pdf

General questions and discussion.

Meeting break at 11:15am
Meeting reconvened at 11:20am

Presentation #8	Architectural Considerations and Managing PMDs Timeline
Presenters	Ali Ghiasi
URL	https://www.ieee802.org/3/df/public/22_02/ghiasi_3df_01a_220215.pdf

Mr. Ghiasi noted that the presentation had been updated to include contributors page and one correction.

General questions and discussion.

During the review of the slide entitled Cu CR 800/1600 GbE FEC Options, it was noted that the PMD sublayers were not shown, so it wasn't clear what should be an AUI. Mr. Ghiasi agreed and noted he would send update. (Update noted above contains all changes).

Chair reviewed the presentations for the 22 Feb Meeting.

Chair reviewed the planned meetings for March session, and reiterated that the planned meetings on 3/5, 3/15 and 3/16 were part of the March 2022 Plenary, and a registration fee was required for attendance

Chair reviewed the ad hocs that had been formed.

Meeting recessed for day at 12:28pm

IEEE P802.3df 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet Task Force

February 2022 Electronic Session

Session reconvened at 10:02 am ET (all times ET), 22 Feb 2022

Meeting called to order by John D'Ambrosia, IEEE P802.3df Task Force Chair

Chair showed the IMAT information.

Chair noted that the information regarding the procedures had been sent out, and requested that individuals review the following IEEE SA policies prior to the interim meeting –
- IEEE SA Patent policy
- IEEE SA Copyright Policy
- IEEE SA Participation Policy

Chair asked if anyone needed to review the policies at that time – there were no requests to do so.

Chair presented the third slide (See Slide #29) of the IEEE SA Patent Policy slides. Chair did call for Potentially Essential Patents, and no one came forward.

Chair presented the second slide (See Slide #34) of the IEEE SA Copyright Policy slides. Chair noted – "By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy."

Chair presented the second slide (See Slide #38) of the IEEE SA Participation Policy slides. Chair noted – "Participants in the IEEE-SA "individual process" shall act independently of others, including employers. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation."

Presentation #9	Baseline proposals for 800GE over eight fiber pairs for 500m and 2km reaches
Presenters	Brian Welch
URL	https://www.ieee802.org/3/df/public/22_02/welch_3df_01a_220222.pdf

General questions and discussion.

Presentation #10	On the technical feasibility of optical 200 Gb/s PAM4
Presenters	Maxim Kuschnerov
URL	https://www.ieee802.org/3/df/public/22_02/kuschnerov_3df_01_220222.pdf

General questions and discussion.

Presentation #11	Modulation proposal for 200G/L solutions for 500m and 2km reaches
Presenters	Brian Welch
URL	https://www.ieee802.org/3/df/public/22_02/welch_3df_02a_220222.pdf

General questions and discussion.

Presentation #12   **Coherent Proposals for 800LR and 800ER**
Presenters   Mike Sluyski
URL   https://www.ieee802.org/3/df/public/22_02/williams_3df_01_220222.pdf

General questions and discussion.

Meeting break at approximately 11:55 pm.
Meeting reconvened at approximately 12:00 pm.

Presentation #13   **Standardizing Coherent Signaling and IEEE P802.3df**
Presenters   John D'Ambrosia
URL   https://www.ieee802.org/3/df/public/22_02/dambrosia_3df_01_220222.pdf

General questions and discussion.

Straw Poll #2	I support the adoption of the following objective: • Define a physical layer specification that supports 400 Gb/s operation: ○ over 4 pairs of SMF with lengths up to at least 2 km
Results All	Yes – 45 No – 1 Need more information – 17 Abstain - 7

Straw Poll #3	I would support the following –
	    A. Adopt the proposal designated as "800G-DR8" in welch_3df_01a_220222 as a baseline (800 Gb/s, over 8 pairs SMF, >=500m)
	    B. Adopted the proposal designated as "800G-DR8+" in welch_3df_01a_220222 as a baseline (800 Gb/s, over 8 pairs SMF, >=2km)		

Results All		Question A	Question B
	Yes –	58	55
	No –	0	0
	Need more information –	5	8
	Abstain -	9	9

Chair reminded the group of the deadline to make presentation requests for the March 2022 session.

Chair reminded the Task Force that the meetings on 08 Mar, 15 Mar, and 16 Mar would require attendees to pay a registration fee.

Meeting recessed at approximately 1pm.

IEEE P802.3df 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet Task Force

February 2022 Electronic Session

Session reconvened at 10:02 am ET (all times ET), 24 Feb 2022

Meeting called to order by John D'Ambrosia, IEEE P802.3df Task Force Chair

Chair showed the IMAT information.

Chair reminded TF of two emails he had sent to the reflector
- Motion about adopting baselines per straw poll 3 per Feb 22 Meeting. Chair indicated that the email should have referred to Straw Poll #2.
- File name in straw poll Feb 22 was incorrect.

Chair noted that the information regarding the procedures had been sent out, and requested that individuals review the following IEEE SA policies prior to the interim meeting –
- IEEE SA Patent policy
- IEEE SA Copyright Policy
- IEEE SA Participation Policy

Chair asked if anyone needed to review the policies at that time – there were no requests to do so.

Chair presented the third slide (See Slide #29) of the IEEE SA Patent Policy slides. Chair did call for Potentially Essential Patents, and no one came forward.

Chair presented the second slide (See Slide #33) of the IEEE SA Copyright Policy slides. Chair noted – "By participating in this activity, you agree to comply with the IEEE Code of Ethics, all applicable laws, and all IEEE policies and procedures including, but not limited to, the IEEE SA Copyright Policy."

Chair presented the second slide (See Slide #37) of the IEEE SA Participation Policy slides. Chair noted – "Participants in the IEEE-SA "individual process" shall act independently of others, including employers. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation."

Chair reminded everyone that presentation requests for the February 2022 session were due this Friday, AoE

Presentation #14	**Modulation Proposal**
Presenters	Chris Cole
URL	https://www.ieee802.org/3/df/public/22_02/cole_3df_01a_220224.pdf

General questions and discussion.

Cole will send an email to the reflector regarding the "noise floor" on PAM4 / PAM6 simulations.

Cole will send an updated presentation, corrected the project # in the footer. Updated noted above.

Presentation #15   **200G PAM4 per Lane C2M Channel Technical Feasibility**
Presenters   Rick Rabinovich
URL   https://www.ieee802.org/3/df/public/22_02/rabinovich_3df_01a_220224.pdf

Mr. Rabinovich noted he would be providing channel data for the Task Force.

It was noted that the presentation was an update of what was currently online (added supporters). It was also noted that Ali Ghiasi's affiliation was incorrect. Rabinovich said he would provide an updated presentation (noted above).

General questions and discussion.

Presentation #16   **Considerations for Modulation Scheme at 200Gbps/lane Electrical**
Presenters   Leesa Noujelm
URL   https://www.ieee802.org/3/df/public/22_02/noujeim_3df_01_220224.pdf

General questions and discussion.
Break at 12:06pm

Meeting reconvened at 12:10pm

Presentation #17   **PAM4 vs. PAM6 modulation choice for 200GEL**
Presenters   Bill Simms
URL   https://www.ieee802.org/3/df/public/22_02/simms_3df_01a_220224.pdf

General questions and discussion.

Straw Poll #4	Would you support PAM4 as the modulation type for 200G/L solutions at 500m and 2km reaches.
Results All	Yes – 80 No – 0 Need more information – 10 Abstain - 7

Motion #1	Adopt the following baselines:
	    A. The proposal designated as "800G-DR8" in welch_3df_01a_220222 as a baseline (800 GbE, over 8 pairs SMF, >=500m)
	    B. The proposal designated as "800G-DR8+" in welch_3df_01a_220222 as a baseline (800 GbE, over 8 pairs SMF, >=2km)

M:	Adee Ran
S:	Ray Nering
802.3 Voters (y/n/a)	Approved by unanimous consent

Presentation #18   **802.3df Leadership Observations: February meeting cycle**
Presenters   Mark Nowell
URL   https://www.ieee802.org/3/df/public/22_02/nowell_3df_01_220224.pdf

Session adjourned at 1:01pm

Attendees (per IMAT)

Name	Employer	Affiliation	3-Feb	15-Feb	22-Feb	24-Feb
Akbaba, Enis	Analog Devices Inc.	Maxim Integrated Products		X	X	X
Bartlett, Josiah		Maxim Integrated Products		X		
Ben-Artsi, Liav	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	X			X
Bernier, Eric		Huawei Technologies Canada; Huawei Technologies Co., Ltd	X	X	X	X
Bliss, William	Broadcom Corporation	Broadcom Corporation		X		X
Bois, Karl	NVIDIA Corporation	NVIDIA Corporation	X	X	X	
Brown, Matthew	Huawei Technologies Canada	Huawei Technologies Canada	X			X
Bruckman, Leon	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X	X
Calvin, John	Keysight Technologies	Keysight Technologies	X	X	X	X
Cassan, Dave	Alphawave	Alphawave	X	X		
Chacon Simon, Geoffrey	Hewlett Packard Enterprise	Synopsys, Inc.	X			
Chang, Yongmao	Inphi Corporation	Source Photonics		X		X
Chen, Chan	Applied Optoelectronics, Inc.	Applied Optoelectronics, Inc.	X	X	X	X
Choudhury, Golam	OFS	OFS	X	X	X	X
D'Ambrosia, John	Futurewei Technologies	Futurewei Technologies, U.S. Subsidiary of Huawei	X	X	X	X
Dawe, Piers J G	NVIDIA	Nvidia	X			X
Deandrea, John	Finisar Corporation	Finisar Corporation	X	X	X	
Diminico, Christopher	M C Communications, LLC	Panduit Corp.				X
Dudek, Michael	Marvell	Marvell				X
Ewen, John	Marvell	Marvell	X	X	X	X
Ferretti, Vincent	Corning Incorporated	Corning Incorporated	X	X		X
FILIPPOU, DIMITRIS		Dimitris Filippou; I2QS			X	X
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd			X	X
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.	X	X		X
Goodwill, Dominic		Huawei Technologies Canada; Huawei Technologies Co., Ltd	X	X	X	X
Gore, Brandon	Samtec, Inc.	Samtec, Inc.	X			X
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.	X			X
Gustlin, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X	X	X
Haasz, Jodi	IEEE-SA	IEEE Standards Association (IEEE-SA)				X
Harstead, Ed	Nokia	Nokia			X	
Haser, Alexandra	Molex Incorporated	Molex Incorporated	X			X
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X		X
Healey, Adam	Broadcom Inc.	Broadcom Inc.	X			X
Heck, Howard	Intel Corporation	Intel Corporation	X			X
Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor	X			X
Huang, Kechao		Huawei Technologies Co., Ltd	X	X	X	X
HUANG, QINHUI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X	X
Huber, Thomas	Nokia	Nokia	X	X	X	X
Hutchins, Jeff	Ranovus	Ranovus		X		X

Name	Affiliation 1	Affiliation 2				
Isono, Hideki	Fujitsu Optical Components Limited	Fujitsu Optical Components Limited	X	X	X	X
Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co., Ltd	X	X	X	X
Jackson, Kenneth	Sumitomo Electric Device Innovations, USA	Sumitomo Electric Industries, LTD	X	X	X	X
Jimenez, Andrew	Anixter Inc.	Anixter Inc.				X
Johnson, John	Broadcom Corporation	Broadcom Corporation	X	X	X	X
Kamino, John	OFS	OFS		X		
Kao, Chienping	Intel Corporation	Cornelis Networks	X	X	X	X
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X	X	X
Kim, Kihong/Joshua	Hirose Electric (USA), Inc.	Hirose Electric (USA), Inc.	X	X	X	X
Kimber, Eric	Semtech Ltd	Semtech Ltd	X			
Kinningham, Alan	I-PEX CONNECTORS	I-PEX (division of Dai-Ichi Seiko)		X	X	X
Klempa, Michael	University of New Hampshire InterOperability Laboratory (UNH-IOL)	Amphenol Corporation	X	X		X
Klingensmith, William	U.S. Federal Government	DoD			X	X
Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.				X
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation	X			
Koehler, Daniel	MorethanIP	Synopsys, Inc.		X	X	
Kondo, Taiji	MegaChips Corporation	Dexerials	X	X	X	X
Kuschnerov, Maxim	Huawei Technologies Duesseldorf GmbH	Huawei Technologies Duesseldorf GmbH	X	X	X	X
Lam, Cedric		Google	X	X		
Lapierre, Dominic		EXFO Inc.	X	X	X	X
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise		X	X	
Lawson, Matthew	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X	X	X
Le Cheminant, Greg	Keysight Technologies	Keysight Technologies	X	X	X	X
Levin, Itamar		Intel Corporation	X	X	X	X
Lewis, David	Lumentum Inc.	Lumentum Inc.		X	X	X
Li, Mike-Peng	Intel Corporation	Intel Corporation	X	X	X	X
Li, Pei-Rong		MediaTek Inc.	X	X	X	X
Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.				X
Lin, Youxi	Huawei Technologies Duesseldorf GmbH	Huawei Technologies Co., Ltd	X		X	X
Liu, Karen	Nubis Communications	Nubis Communications	X		X	X
Lu, Yuchun	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd		X		
Lusted, Kent	Intel Corporation	Intel Corporation	X			X
Mak, Gary	Inphi Corporation	inphi	X	X	X	X
Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.	X	X	X	
Malicoat, David	Malicoat Networking Solutions	Malicoat Networking Solutions; SENKO Advanced Components	X	X	X	X
Maniloff, Eric	Ciena Corporation	Ciena Corporation	X	X	X	X
Marris, Arthur	Cadence Design Systems, Inc.	Cadence Design Systems, Inc.	X			
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.	X			X

Name						
Meltser, Roman		NVIDIA Corporation		X		
mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X		X	X
Mitcheltree, Tom	US Conec, Ltd.	US Conec, Ltd.			X	X
Mohajeri, Hessam	Cadence Design Systems, Inc.	Cadence Design Systems, Inc.		X		
Moorwood, Charles	Keysight Technologies	Keysight Technologies	X	X	X	X
Mu, Jianwei		Hisense	X	X	X	X
Mueller, Thomas	Rosenberger	Rosenberger		X		
Muller, Shimon	Enfabrica Corp.	Enfabrica Corp.	X	X	X	X
Murty, Ramana	Broadcom Inc.	Broadcom Corporation		X	X	X
Muth, Karlheinz	Broadcom Corporation	Broadcom Corporation				X
Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X	X	X
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.			X	X
Nicholl, Shawn	Xilinx	Xilinx	X			
Nikolich, Paul	SELF FUNDED	Self Employed			X	
Noujeim, Leesa	Google	Google	X	X		X
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X	X	X
Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.	X	X	X	X
Omori, Kumi	NEC Corporation	NEC Corporation	X	X	X	X
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.	X	X	X	X
Palkert, Thomas	Macom, Samtec	Samtec-Macom	X	X	X	X
PARK, CHUL SOO	Juniper Networks Inc.	Juniper Networks, Inc.	X	X	X	X
Parsons, Earl	CommScope, Inc.	CommScope, Inc.	X			X
peng, semmy		Huawei Technologies Co., Ltd		X		
Pepper, Gerald	Keysight Technologies	Keysight Technologies	X		X	X
Piehler, David	Dell Technologies	Dell	X		X	
Pimpinella, Rick	Panduit Corp.	Panduit Corp.	X	X		X
Pittala, Fabio	Huawei Technologies Duesseldorf GmbH	Huawei Technologies Duesseldorf GmbH	X	X	X	X
Rabinovich, Rick	Keysight Technologies	Keysight Technologies				X
Radhamohan, Rajeshmohan	MAXLINEAR INC	Cisco Systems, Inc.	X	X	X	
Rahn, Jeffrey	Facebook	Facebook			X	X
Ramesh, Sridhar	MaxLinear	MAXLINEAR INC	X			
Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.	X			X
Rechtman, Zvi	NVIDIA	NVIDIA	X	X	X	X
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X	X
Rodes, Roberto	II-VI	II-VI	X	X	X	X
Sakai, Toshiaki	Socionext Inc.	socionext	X			X
Sambasivan, Sam	AT&T	AT&T	X	X	X	
Savi, Olindo	Hubbell Incorporated	Hubbell Incorporated	X	X	X	
Sella, Omer		Imperial College London			X	
Shahramian, Shayan	Alphawave IP	Alphawave	X			X
Shanbhag, Megha	Tyco	TE Connectivity				X

Shrikhande, Kapil	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	X		X	
Shukla, Priyank	Synopsys, Inc.	Synopsys, Inc.		X	X	X
Simms, William	NVIDIA Corporation	NVIDIA Corporation	X	X	X	X
Slavick, Jeff	Broadcom Inc	Broadcom Inc			X	X
Sluyski, MIke		Cisco Systems, Inc.			X	
Sommers, Scott	Molex LLC	Molex Incorporated	X			X
Son, Yung Sung	Optomind Inc	Optomind Inc	X	X	X	X
Sorbara, Massimo	GLOBALFOUNDRIES	GLOBALFOUNDIRES	X	X		X
Sprague, Edward	Infinera Corporation	Infinera Corporation	X	X	X	
Srivastava, Atul	NEL-America	NTT Electronics	X	X	X	X
Stassar, Peter	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X		X	X
Stone, Robert	Broadcom Corporation	Meta	X		X	X
Sun, Junqing	Credo Semiconductor	Credo Semiconductor			X	X
Sun, Yi		OFS	X		X	
Tailor, Bharat	Semtech Canada Corporation	Semtech Canada Corporation	X	X	X	X
TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	FUJITSU LIMITED	X	X		
Terada, Masaru	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC	X	X	X	X
Theodoras, James	HG Genuine	HG Genuine	X			X
Thompson, lance	II-VI	Finisar Corporation			X	
Toifl, Thomas		Cisco Systems, Inc.	X			
tomofuji, hiroaki		FUJITSU		X		
Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.	X	X	X	X
Tracy, Nathan	TE Connectivity	TE Connectivity	X		X	X
Tran, Viet	Keysight Technologies	Keysight Technologies	X	X		X
Trowbridge, Stephen	Nokia	Nokia	X		X	
Ulrichs, Ed	Intel Corporation	Intel Corporation	X			X
Venkataraman, Srinivas		Facebook	X			X
Vitali, Marco	Sicoya	Sicoya	X	X	X	X
Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)	X	X	X	X
Wang, Ruoxu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X	X
Wang, Xinyuan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	X	X	X	
Weaver, James	Arista Networks	Arista Networks	X			X
Welch, Brian	Cisco Systems, Inc.	Luxtera	X	X	X	X
Whiteman, Cameron	Infinera Corporation	Infinera Corporation	X			
Williams, Tom	Cisco Systems, Inc.	Cisco Systems, Inc.		X		
Wu, Mau-Lin	MediaTek Inc.	MediaTek Inc.	X			X
Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd				X
Young, James	CommScope, Inc.	CommScope	X		X	
Zebian, Sara		Google				X
Zhang, Bo	Marvell Technology, Inc	Marvell Technology, Inc		X	X	
Zhang, Sen		Huawei Technologies Co., Ltd	X			

Zhiwei, Yang	ZTE Corporation	ZTE Corporation		X		
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd		X	X	X
Zivny, Pavel	Tektronix, Inc.	Tektronix, Inc.	X			X

Straw poll Summary

Straw Poll #1	I support the proposed direction for 800GbE electrical interfaces and PMDs using 100 Gbps/lane signaling, per lusted_3df_01a_220203.pdf, slides 5-7
Results All	Yes – 41 No – 0 Need more information – 22 Abstain - 8

Straw Poll #2	I support the adoption of the following objective: • Define a physical layer specification that supports 400 Gb/s operation: o over 4 pairs of SMF with lengths up to at least 2 km
Results All	Yes – 45 No – 1 Need more information – 17 Abstain - 7

Straw Poll #3	I would support the following –
	   C. Adopt the proposal designated as "800G-DR8" in welch_3df_01a_220222 as a baseline (800 Gb/s, over 8 pairs SMF, >=500m)
	   D. Adopted the proposal designated as "800G-DR8+" in welch_3df_01a_220222 as a baseline (800 Gb/s, over 8 pairs SMF, >=2km)

Results All		Question A	Question B
	Yes –	58	55
	No –	0	0
	Need more information –	5	8
	Abstain -	9	9

Straw Poll #4	Would you support PAM4 as the modulation type for 200G/L solutions at 500m and 2km reaches.
Results All	Yes – 80 No – 0 Need more information – 10 Abstain - 7

Motions Summary

Motion #1	Adopt the following baselines: A. The proposal designated as "800G-DR8" in welch_3df_01a_220222 as a baseline (800 GbE, over 8 pairs SMF, >=500m) B. The proposal designated as "800G-DR8+" in welch_3df_01a_220222 as a baseline (800 GbE, over 8 pairs SMF, >=2km)
M:	Adee Ran
S:	Ray Nering
802.3 Voters (y/n/a)	Approved by unanimous consent